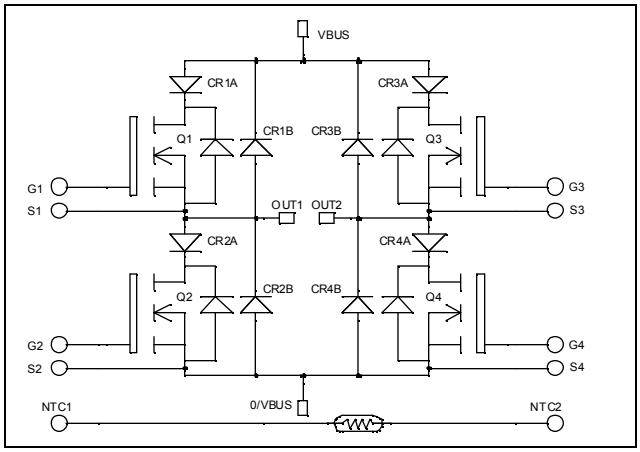
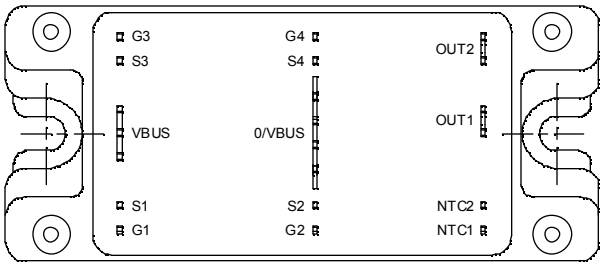
APTM100H45ST

Full bridge
Series & parallel diodes
MOSFET Power Module

V_{DSS} = 1000V
R_{DSon} = 450mΩ max @ Tj = 25°C
I_D = 18A @ Tc = 25°C





Application

- Motor control
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7® MOSFETs
  - Low R_{DSon}
  - Low input and Miller capacitance
  - Low gate charge
  - Avalanche energy rated
  - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		1000	V
I_D	Continuous Drain Current	T_c = 25°C	18	A
		T_c = 80°C	14	
I_{DM}	Pulsed Drain current		72	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		450	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	357	W
I_{AR}	Avalanche current (repetitive and non repetitive)		18	A
E_{AR}	Repetitive Avalanche Energy		50	mJ
E_{AS}	Single Pulse Avalanche Energy		2500	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed.

All ratings @ T_j = 25°C unless otherwise specified

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
BV_{DSS}	Drain - Source Breakdown Voltage	V_{GS} = 0V, I_D = 250µA		1000			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{GS} = 0V, V_{DS}= 1000V	T_j = 25°C			100	µA
		V_{GS} = 0V, V_{DS}= 800V	T_j = 125°C			500	
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 9A				450	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 2.5mA		3		5	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±30 V, V_{DS} = 0V				±100	nA

Dynamic Characteristics

Symbol	*Characteristic*	*Test Conditions*	*Min*	*Typ*	*Max*	*Unit*
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1MHz		4350		pF
C_{oss}	Output Capacitance			715		
C_{rss}	Reverse Transfer Capacitance			120		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 500V I_D = 18A		154		nC
Q_{gs}	Gate – Source Charge			26		
Q_{gd}	Gate – Drain Charge			97		
$T_{d(on)}$	Turn-on Delay Time	**Inductive switching @ 125°C** V_{GS} = 15V V_{Bus} = 667V I_D = 18A R_G = 5Ω		10		ns
T_r	Rise Time			12		
$T_{d(off)}$	Turn-off Delay Time			121		
T_f	Fall Time			35		
E_{on}	Turn-on Switching Energy ❶	**Inductive switching @ 25°C** V_{GS} = 15V, V_{Bus} = 667V I_D = 18A, R_G = 5Ω		639		µJ
E_{off}	Turn-off Switching Energy ❷			380		
E_{on}	Turn-on Switching Energy ❶	**Inductive switching @ 125°C** V_{GS} = 15V, V_{Bus} = 667V I_D = 18A, R_G = 5Ω		1046		µJ
E_{off}	Turn-off Switching Energy ❷			451		

❶ E_{on} includes diode reverse recovery.
❷ In accordance with JEDEC standard JESD24-1.

Series diode ratings and characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
$I_{F(AV)}$	Maximum Average Forward Current	50% duty cycle	T_c = 85°C		30		A
V_F	Diode Forward Voltage	I_F = 30A			1.1	1.15	V
		I_F = 60A			1.4		
		I_F = 30A	T_j = 125°C		0.9		
t_{rr}	Reverse Recovery Time	I_F = 30A V_R = 133V di/dt = 200A/µs	T_j = 25°C		24		ns
			T_j = 125°C		48		
Q_{rr}	Reverse Recovery Charge	I_F = 30A V_R = 133V di/dt = 200A/µs	T_j = 25°C		33		nC
			T_j = 125°C		150		

Parallel diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	Maximum Average Forward Current	50% duty cycle	T_c = 65°C		30		A
V_F	Diode Forward Voltage	I_F = 30A			1.9	2.3	V
		I_F = 60A			2.2		
		I_F = 30A	T_j = 125°C		1.7		
t_{rr}	Reverse Recovery Time	I_F = 30A V_R = 667V di/dt = 200A/µs	T_j = 25°C		290		ns
			T_j = 125°C		390		
Q_{rr}	Reverse Recovery Charge	I_F = 30A V_R = 667V di/dt = 200A/µs	T_j = 25°C		670		nC
			T_j = 125°C		2350		

Thermal and package characteristics

Symbol	Characteristic			Min	Typ	Max	Unit
R_{thJC}	Junction to Case		Transistor			0.35	°C/W
			Diode			1.2	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, I isol<1mA, 50/60Hz			2500			V
T_J	Operating junction temperature range			-40		150	°C
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To Heatsink	M5			4.7	N.m
Wt	Package Weight					160	g

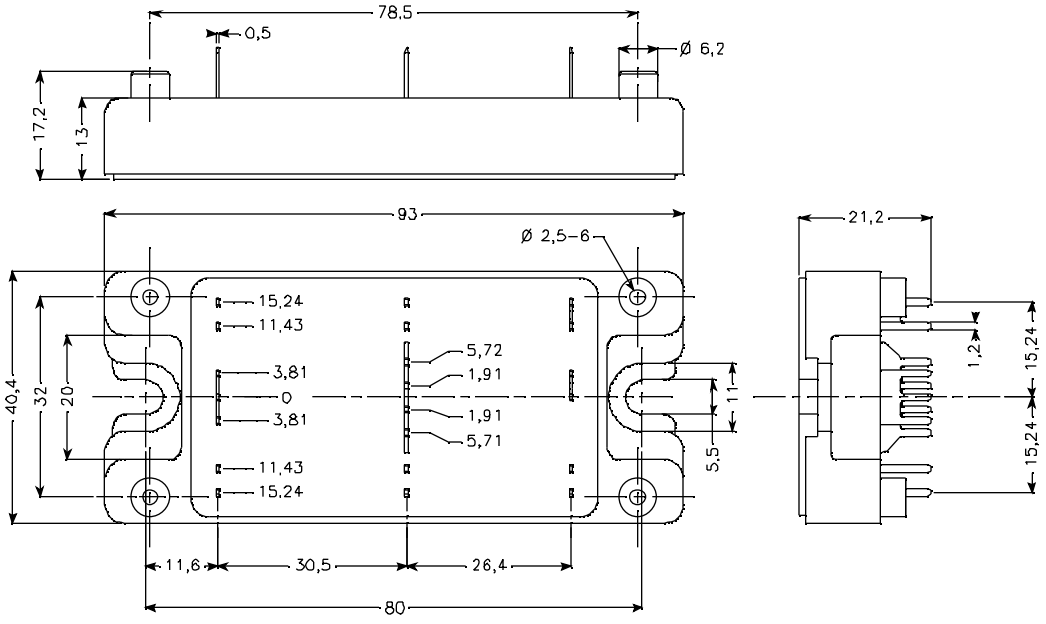
Temperature sensor NTC

Symbol	Characteristic	Min	Typ	Max	Unit
R_{25}	Resistance @ 25°C		68		kΩ
$B_{25/85}$	T_{25} = 298.16 K		4080		K

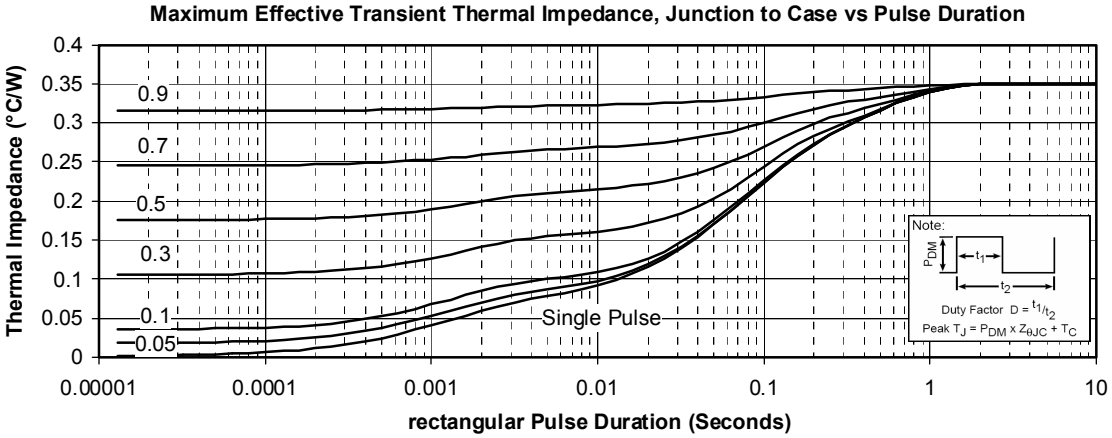
$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

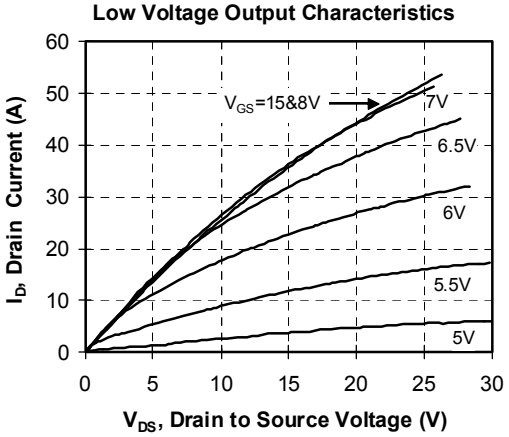
T: Thermistor temperature
R_T: Thermistor value at T

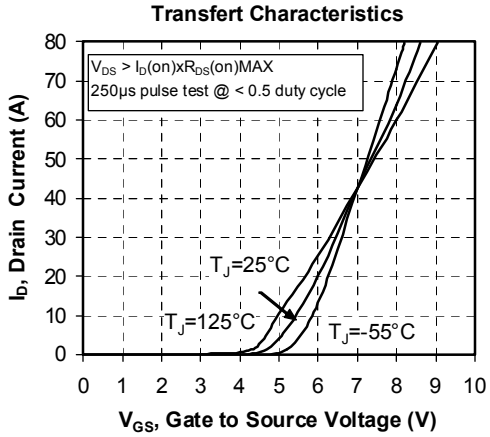
Package outline

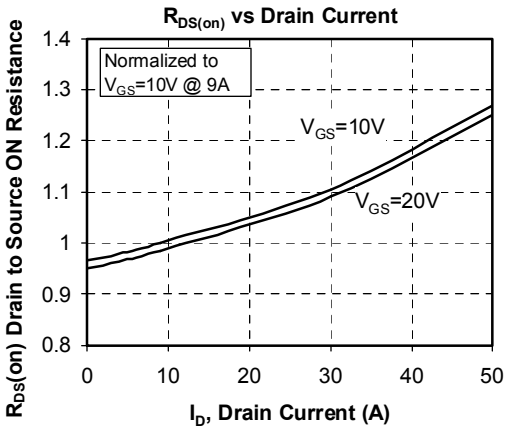


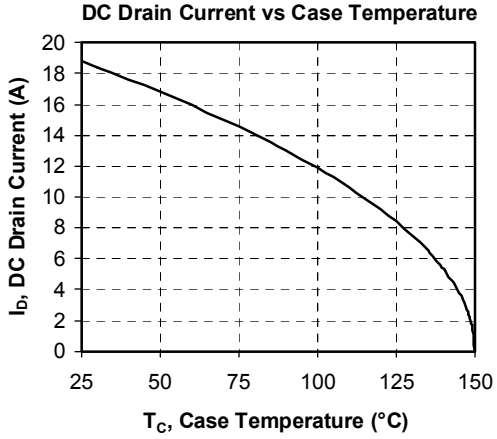
Typical Performance Curve



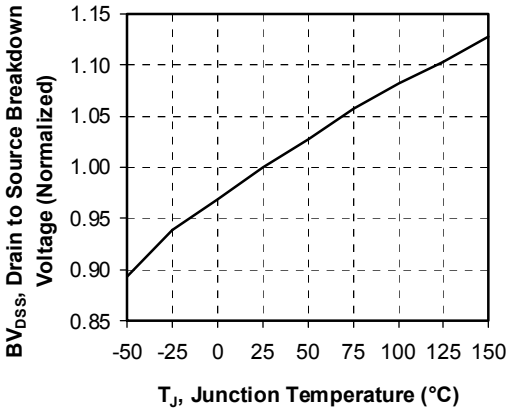




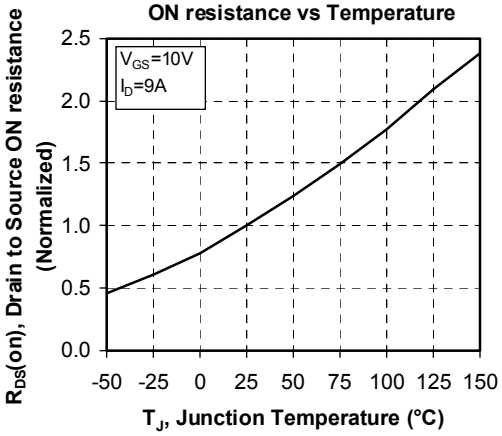




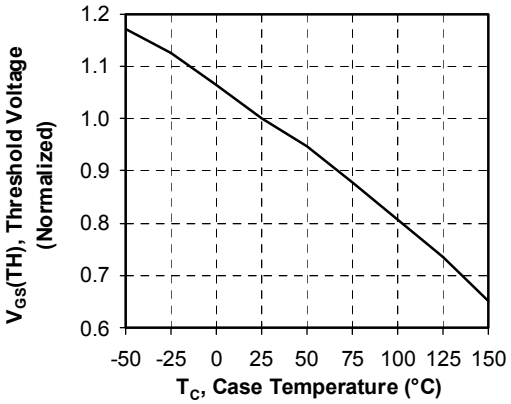
Breakdown Voltage vs Temperature



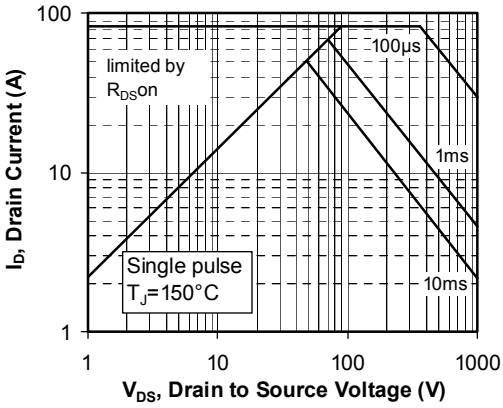
ON resistance vs Temperature



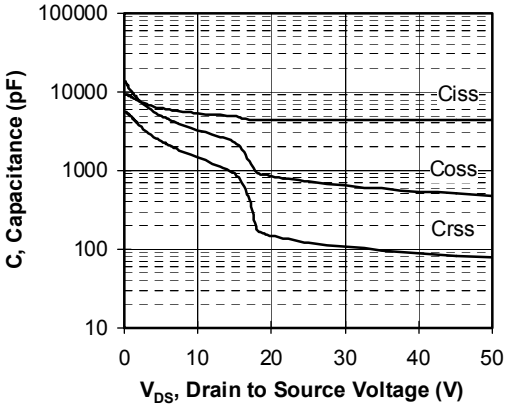
Threshold Voltage vs Temperature



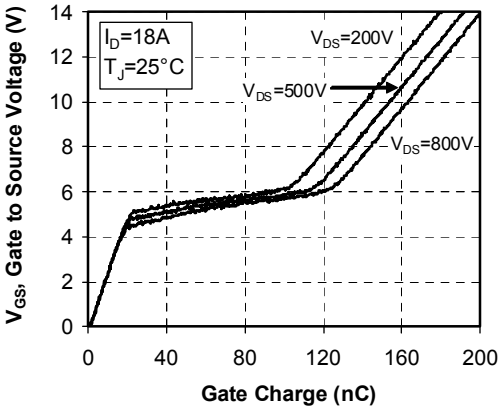
Maximum Safe Operating Area



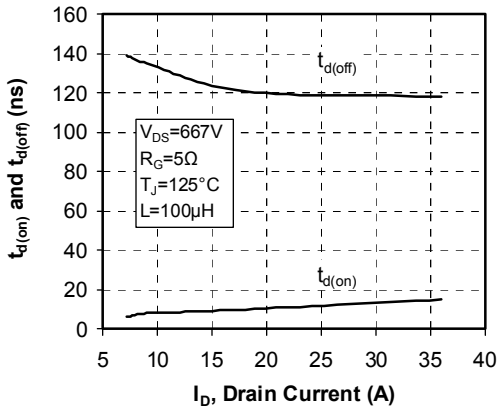
Capacitance vs Drain to Source Voltage



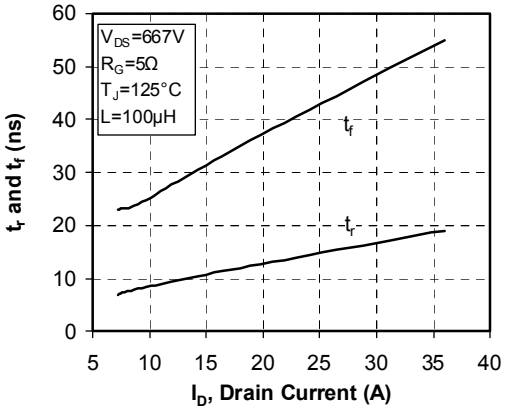
Gate Charge vs Gate to Source Voltage



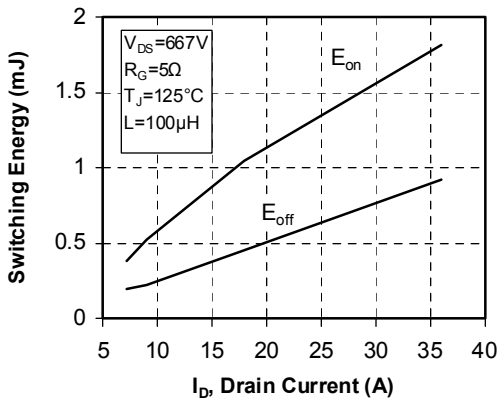
Delay Times vs Current



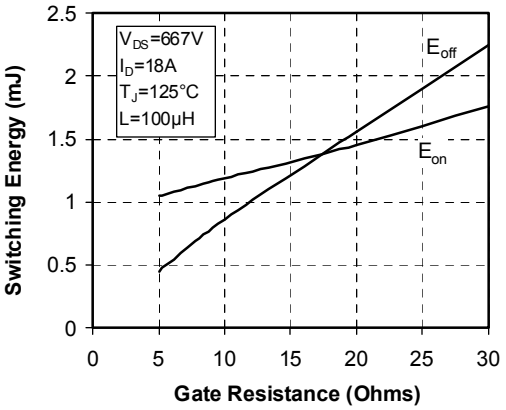
Rise and Fall times vs Current



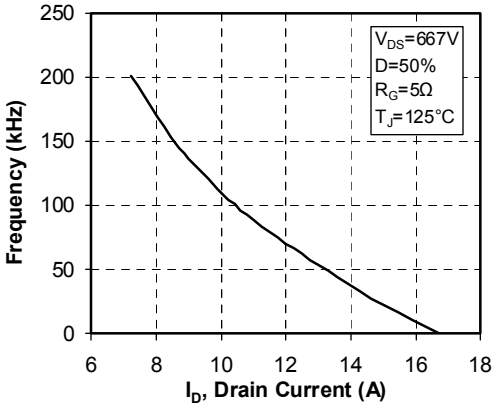
Switching Energy vs Current



Switching Energy vs Gate Resistance



Operating Frequency vs Drain Current



Source to Drain Diode Forward Voltage